

PATENT
AMENDMENT

IN THE CLAIMS:

Please add new claims 17 and 18 as follows:

1 —17. (New) A method of adhesive bonding comprising:

2 providing an adherend;

3 providing a substrate;

4 providing a photocurable adhesive composition containing an adhesive and
5 microspheres;

6 extruding said photocurable adhesive composition onto at least one of said
7 adherend and said substrate;

8 pressing said adherend and said substrate together with said photocurable
9 adhesive composition therebetween; and

10 photocuring said photocurable adhesive composition to form an at least partially
11 cured adhesive composition whereby said adherend and substrate are bonded together.

1 —18. (New) A method of adhesive bonding comprising:

2 providing an adherend;

3 providing a substrate;

4 providing a photocurable adhesive composition containing an adhesive and
5 microspheres, said photocurable adhesive being a pseudoplastic flow material;

6 flowing said photocurable adhesive composition onto at least one of said adherend
7 and said substrate;

8 pressing said adherend and said substrate together with said photocurable
9 adhesive composition therebetween; and

10 photocuring said photocurable adhesive composition to form an at least partially
11 cured adhesive composition whereby said adherend and substrate are bonded together.